

Title (en)

LED DIE DISPERSAL IN DISPLAYS AND LIGHT PANELS WITH PRESERVING NEIGHBORING RELATIONSHIP

Title (de)

LED-MATRIXVERTEILUNG BEI ANZEIGEN UND LEUCHTPANELEN MIT ERHALTUNG VON NACHBARSCHAFTSBEZIEHUNGEN

Title (fr)

DISPERSION DE PUCES DE DEL DANS DES DISPOSITIFS D'AFFICHAGE ET PANNEAUX D'ÉCLAIRAGE À PRÉSERVATION DE RELATION DE VOISINAGE

Publication

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Application

EP 13851524 A 20131024

Priority

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- US 2013066610 W 20131024

Abstract (en)

[origin: US2014120640A1] A method of dispersing semiconductor chips from a wafer of semiconductor chips onto a substrate while preserving the neighboring relationship of each chip to each adjacent chip is disclosed. The method includes dispersing the wafer into sequential columns of semiconductor chips with a first pitch between columns while preserving the neighboring relationship and sequentially dispersing the columns of semiconductor chips into rows of individual chips with a second pitch between rows onto a substrate while preserving the neighboring relationship.

IPC 8 full level

H01L 21/00 (2006.01)

CPC (source: EP US)

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